

Listing of Claims

Claims 1-14 (Canceled)

Claim 15. (Currently amended) A method for depositing a solderable finish on an electronic device substrate, the method comprising;

electrolytically depositing onto the substrate a metal from an electroplating composition that comprises ~~at least one~~ or more soluble metal salt, an electrolyte, at least ~~on one~~ grain refiner/stabilizer additive comprising one or more ~~non-aromatic compounds having π electrons~~ that can be delocalized hydroxylated gamma-pyrone compounds.

Claim 16. (Original) The method of claim 15 wherein the metal salt comprises tin.

Claim 17. (Canceled)

Claim 18. (Currently amended) The method of claim 15 wherein the grain refiner/stabilizer additive is present at ~~concentration~~ concentrations of between about 2 mg and about 10,000 mg per liter of the electroplating composition.

Claim 19. (Currently amended) The method of claim 15 wherein the stabilizer additive is present at ~~concentration~~ concentrations of between about 50 mg and about 2000 mg per liter of the electroplating composition.

Claim 20. (Original) The method of claim 15 further comprising a brightener agent.

Claim 21. (Original) The method of claim 15 wherein the composition further comprises a suppressor agent.

Claim 22. (Original) The method of claim 15 wherein the composition further comprises a leveler agent.

Claim 23. (Original) The method of claim 15 wherein the substrate is a printed circuit board substrate or semiconductor with one or more microvias.

Claim 24. (Original) The method of claim 15 wherein the substrate is a microchip module substrate.

Claim 25. (Canceled)

Claim 26. (Canceled)

Claim 27. (New) The method of claim 15 wherein the hydroxylated gamma-pyrone comprises Kojic acid, meconic acid, comenic acid, maltol, or ethylmaltol.

Claim 28. (New) The method of claim 15 wherein the soluble metal salt comprises a salt of tin, zinc, copper, nickel, gold, silver, bismuth, indium or antimony.

Claim 29. (New) The method of claim 15 wherein the metal is a tin alloy.

Claim 30. (New) The method of claim 29 wherein the tin alloy is an alloy of tin-silver or tin-copper.

Claim 31. (New) the method of claim 15 wherein the metal is a zinc alloy.